

102590-2026 - Result

Finland – Miscellaneous general and special-purpose machinery – Semi-Automatic Wafer Grinder

OJ S 30/2026 12/02/2026

Contract or concession award notice – standard regime

Supplies

1. Buyer

1.1. Buyer

Official name: VTT Technical Research Centre of Finland Ltd

Email: kilpailutus@vtt.fi

Legal type of the buyer: Public undertaking

Activity of the contracting authority: Economic affairs

2. Procedure

2.1. Procedure

Title: Semi-Automatic Wafer Grinder

Description: The object of the tender was a Semi-Automatic Wafer Grinder with manual wafer loading and unloading on the chuck table (later also “Equipment”), capable of thinning Si, SiC, LiNbO₃ and other typical semi-conducting wafers of 200 and 300 mm diameter to varying thicknesses with end-point control, TTV profile control, capability to thin wafers down to 10um thickness with supporting tape and capability to grind only a determined distance from edge-to-center. Equipment had to be new. The tool had to comply with cleanroom equipment standard safety and contamination requirements. The object of the tender process was described in more detail in the invitation to tender documents.

Procedure identifier: dde3f9e2-2ac9-4d69-a9f6-951468ab0463

Previous notice: 6aacabe8-61fa-47fd-a3ce-0f2053b22080-01

Internal identifier: Reg.no. 63/206/2025

Type of procedure: Open

The procedure is accelerated: no

Main features of the procedure: The tender process was based on the open procedure applicable to contracts that exceed the EU procurement threshold.

2.1.1. Purpose

Main nature of the contract: Supplies

Main classification (cpv): 42900000 Miscellaneous general and special-purpose machinery

2.1.2. Place of performance

Postal address: Tekniikantie 17

Town: Esp

Postcode: 02600

Country subdivision (NUTS): Helsinki-Uusimaa (FI1B1)

Country: Finland

Additional information: Please see the invitation to tender.

2.1.4. General information

Additional information: The object of the tender process was described in more detail in the invitation to tender documents.

Legal basis:

Directive 2014/24/EU

5. Lot

5.1. Lot: LOT-0000

Title: Semi-Automatic Wafer Grinder

Description: The object of the tender was a Semi-Automatic Wafer Grinder with manual wafer loading and unloading on the chuck table (later also "Equipment"), capable of thinning Si, SiC, LiNbO₃ and other typical semi-conducting wafers of 200 and 300 mm diameter to varying thicknesses with end-point control, TTV profile control, capability to thin wafers down to 10um thickness with supporting tape and capability to grind only a determined distance from edge-to-center. Equipment had to be new. The tool had to comply with cleanroom equipment standard safety and contamination requirements. The object of the tender process was described in more detail in the invitation to tender documents.

Internal identifier: Reg.no. 63/206/2025

5.1.1. Purpose

Main nature of the contract: Supplies

Main classification (cpv): 42900000 Miscellaneous general and special-purpose machinery

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Postal address: Tekniikantie 17

Town: Esp

Postcode: 02600

Country subdivision (NUTS): Helsinki-Uusimaa (FI1B1)

Country: Finland

Additional information: Please see the invitation to tender.

5.1.3. Estimated duration

Duration: 24 Months

5.1.6. General information

Procurement Project not financed with EU Funds.

The procurement is covered by the Government Procurement Agreement (GPA): yes

Additional information: The object of the tender process was described in more detail in the invitation to tender documents.

5.1.7. Strategic procurement

Social objective promoted: Human rights due diligence in global supply chains

5.1.10. Award criteria

Criterion:

Type: Price

Description: The evaluation of the tenders was described in section 'Grounds for decision'.

Category of award weight criterion: Weight (percentage, exact)

Award criterion number: 100

5.1.15. Techniques

Framework agreement:

No framework agreement

Information about the dynamic purchasing system:

No dynamic purchase system

5.1.16. Further information, mediation and review

Review organisation: Markkinaoikeus

Information about review deadlines: Muutoksenhaku aika määräytyy hankintalain (1397/2016) mukaisesti.

Organisation providing additional information about the procurement procedure: VTT

Technical Research Centre of Finland Ltd

6. Results

Value of all contracts awarded in this notice: 325 000,00 EUR

6.1. Result lot identifier: LOT-0000

Winner selection status: At least one winner was chosen.

6.1.2. Information about winners

Winner:

Official name: DISCO HI-TEC EUROPE GmbH

Tender:

Tender identifier: tenderReference-4530412-892050

Identifier of lot or group of lots: LOT-0000

Value of the tender: 325 000,00 EUR

Subcontracting: No

Contract information:

Identifier of the contract: EQUIPMENT PURCHASE AGREEMENT 63/206/2025 Semi-Automatic Wafer Grinder

Date of the conclusion of the contract: 03/02/2026

6.1.4. Statistical information

Received tenders or requests to participate:

Type of received submissions: Tenders from tenderers registered in other European Economic Area countries than the country of the buyer

Number of tenders or requests to participate received: 1

8. Organisations

8.1. ORG-0001

Official name: Markkinaoikeus

Registration number: 3006157-6

Postal address: Radanrakentajantie 5

Town: Helsinki

Postcode: 00520

Country subdivision (NUTS): Helsinki-Uusimaa (FI1B1)

Country: Finland

Email: markkinaoikeus@oikeus.fi

Telephone: +358 295643300

Internet address: <http://www.oikeus.fi/markkinaoikeus>

Roles of this organisation:

Review organisation

8.1. ORG-0002

Official name: VTT Technical Research Centre of Finland Ltd

Registration number: 2647375-4

Postal address: P.O. Box 1000, VTT

Town: Espoo

Postcode: 02044

Country subdivision (NUTS): Helsinki-Uusimaa (FI1B1)

Country: Finland

Contact point: VTT Technical Research Centre of Finland Ltd

Email: kilpailutus@vtt.fi

Telephone: +358 20722111

Internet address: <https://www.vttresearch.com/fi>

Roles of this organisation:

Buyer

Organisation providing additional information about the procurement procedure

8.1. ORG-0003

Official name: DISCO HI-TEC EUROPE GmbH

Size of the economic operator: Large

Registration number: DE131174016

Postal address: Liebigstr. 8

Town: Kirchheim b. München

Postcode: 85551

Country subdivision (NUTS): München, Landkreis (DE21H)

Country: Germany

Roles of this organisation:

Tenderer

Winner of these lots: LOT-0000

8.1. ORG-0004

Official name: Hansel Oy (Hilma)

Registration number: FI09880841

Postal address: Mannerheiminaukio 1a

Town: Helsinki

Postcode: 00100

Country subdivision (NUTS): Helsinki-Uusimaa (FI1B1)

Country: Finland

Contact point: eSender

Email: tekninen@hankintailmoitukset.fi

Telephone: 029 55 636 30

Internet address: <http://hankintailmoitukset.fi>

Roles of this organisation:

TED eSender

Notice information

Notice identifier/version: ee2347f9-db93-4e18-946a-1932c665cfc5 - 01

Form type: Result

Notice type: Contract or concession award notice – standard regime

Notice subtype: 29

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